(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
5 February 2004 (05.02.2004)

PCT

(10) International Publication Number
WO 2004/012262 A3

(51) International Patent Classification[7]: H01L 23/498, 23/538, 25/065

(21) International Application Number: PCT/US2003/023405

(22) International Filing Date: 25 July 2003 (25.07.2003)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
60/399,091 26 July 2002 (26.07.2002) US
10/624,787 21 July 2003 (21.07.2003) US

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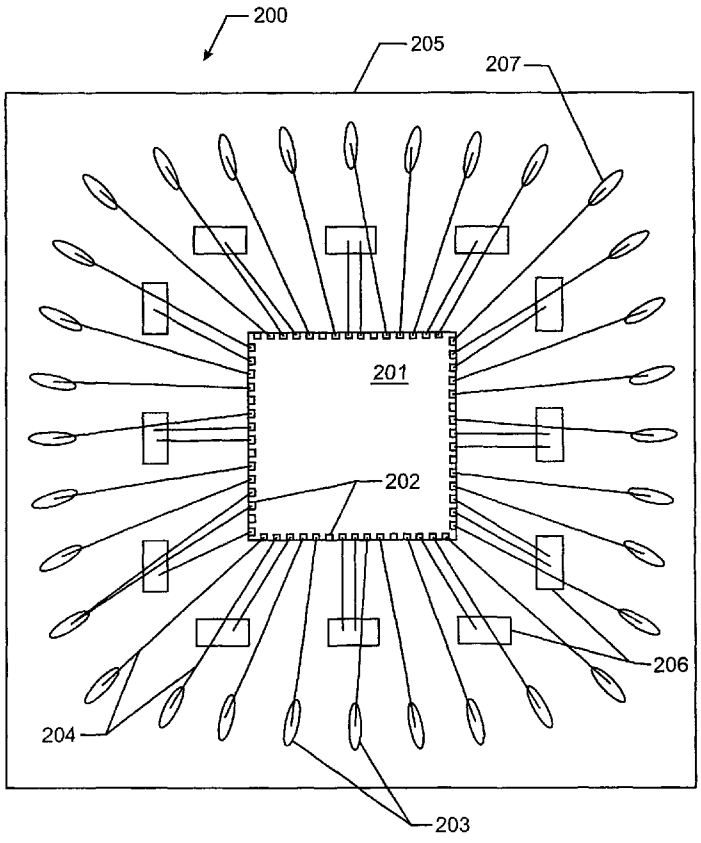
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(81) Designated States *(national)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States *(regional)*: ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE,

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(54) Title: METHOD FOR ACCOMMODATING SMALL MINIMUM DIE IN WIRE BONDED AREA ARRAY PACKAGES



(57) Abstract: An area array package comprising a die attach area for attaching a die to a substrate, a network of staggered bond fingers, and a network of bond islands for coupling bond wires between the bond islands and die bond pads is provided. A network of package leads, for example, a network of solder balls in a ball grid array, is depopulated to permit greater trace route flexibility and via placement within the substrate. Stacked die and multi-chip packages are also disclosed. A method for accommodating a high pin-count die in an area array package is also included

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ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— *with international search report*

— *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments*

(88) Date of publication of the international search report:
8 April 2004

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.